

SPEC NO.	SP03AE24500-0050	ISSUED DATE	2026.06.03	PUBLISHED BY
PRODUCT NAME	DCAJ0S10	VERSION	02	
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SPECIFICATION

SPEC NO.	:	SP03AE24500-0050
PART NO.	:	43A15G03000D21T
PRODUCT NAME	:	DCAJ0S10
DESCRIPTION	:	Dielectric Chip Antenna (3.23x1.66x1.23 mm) RoHS Compliant Product CIROCOMM
MANUFACTURER	:	No. 37, Gongye S. Rd., Guantian Dist., Tainan City 720006, Taiwan (R.O.C.)

REVISION STATUS

VERSION	DATE	PAGE	REVISION DESCRIPTION	PREPARED	CHECKED	APPROVED
01	2022.05.20	Whole	New Issued.	翁秀惠	馬得淞	張敦信、吳佳宗
02	2026.06.03	P.1&2	Add Manufacturer & Modify table1 no.3 Peak Gain 2.7→2.71dBi.	翁秀惠	陳勇廷	張敦信、吳佳宗

Prepared By	Checked By	Approved By
翁秀惠	陳勇廷	張敦信 吳佳宗

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CIROCOMM TECHNOLOGY .

PART NUMBER: 43A15G03000D21T

1. Scope

This specification covers the [dielectric chip antenna](#) for [Bluetooth / WLAN Applications](#).

2. Name of the product

This product is named "[Dielectric Chip Antenna](#)".

3. Electrical characteristics

3-1 Electrical characteristics of antenna

The antenna has the electrical characteristics given in Table 1 under the *cirocomm* standard installation conditions shown in the figure of Evaluation Board.

Table 1

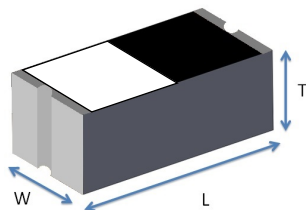
No	Parameter	Specification
1	Working Frequency	2400~2500 MHz
2	Return Loss	-6.5 dB (Max)
3	Peak Gain	2.71 dBi
4	Impedance	50 Ohm
5	Operating Temperature	-40°C ~ +110°C
6	Maximum Power	4 W
7	Resistance to Soldering Heats	10 sec. (@ 260°C)
8	Polarization	Linear
9	Azimuth	Omni-directional
10	Termination	Cu / Sn (Leadless)

* Actual performance will depend on customer device environment.



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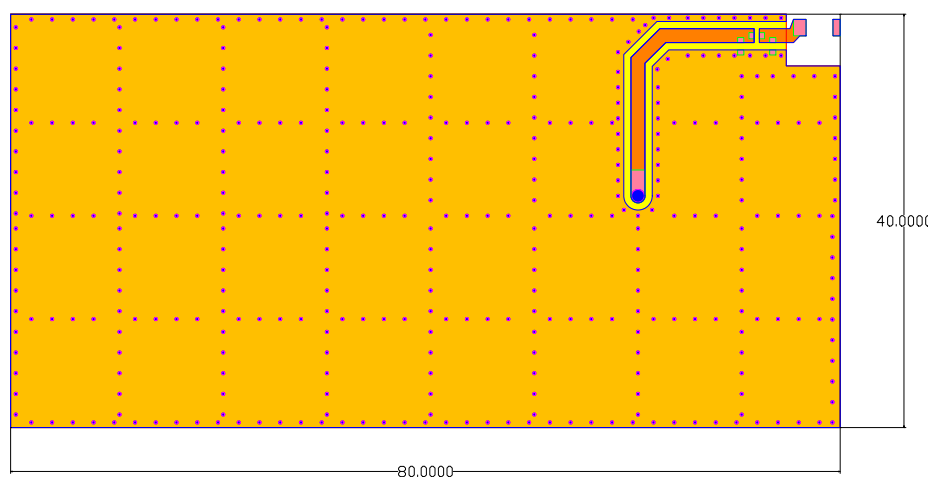
4. Antenna Dimension



	Dimension (mm)
L	3.23 ± 0.20
W	1.66 ± 0.20
T	1.23 ± 0.20

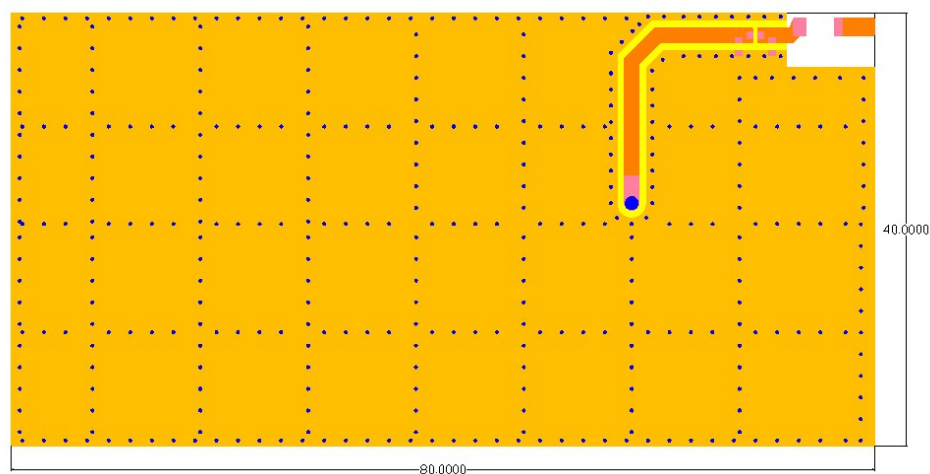
5.Recommended PCB Pattern

5-1.Evaluation Board Dimension



5-2.Evaluation Board Dimension

(若淨空區夠大，建議使用此Layout，效能較佳)



Feed Line



TOP Copper



VIA

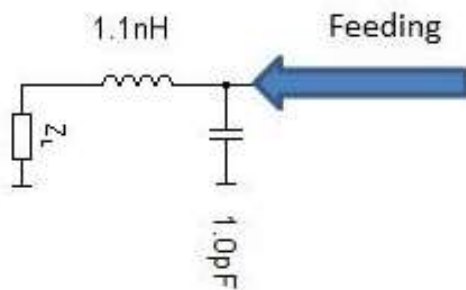
Unit : mm

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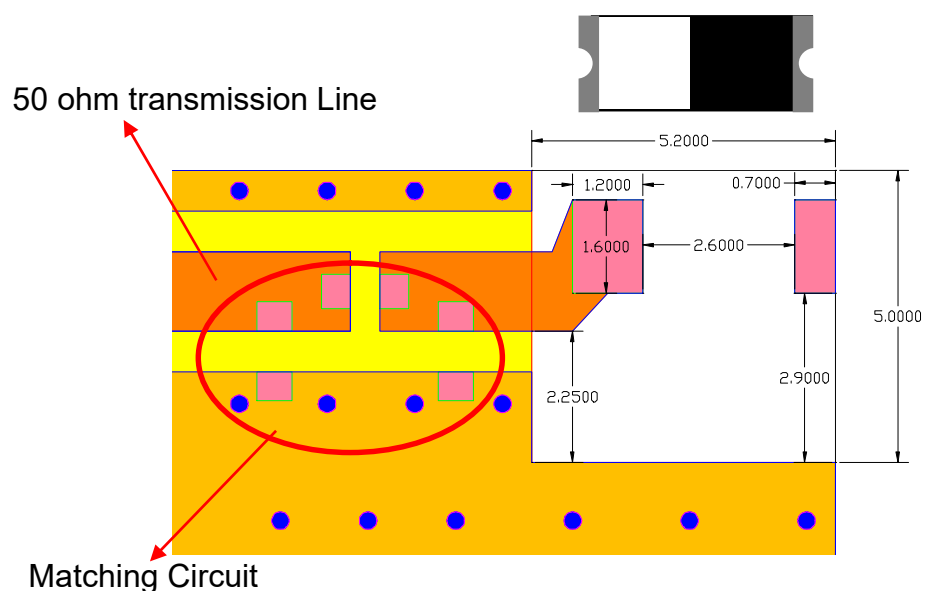
Suggested Matching Circuit

重要資訊：

匹配元件建議使用精準度高的電感 $\pm 0.1 \sim 0.3 \text{ nH}$ 、電容 $\pm 0.1 \text{ pF}$

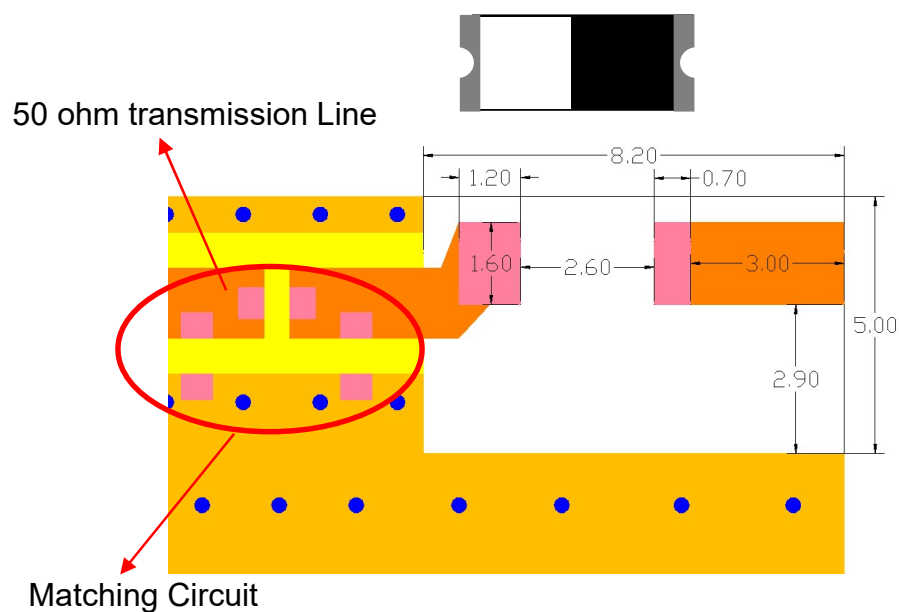


5-3 Layout Dimensions in Clearance area (Size=5.2*5.0mm)



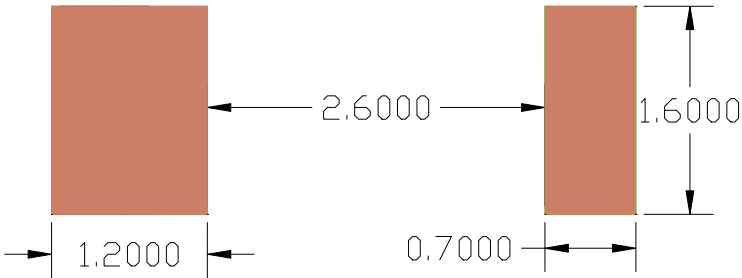
5-4 Layout Dimensions in Clearance area (Size=8.2*5.0mm)

(若淨空區夠大，建議使用此Layout，效能較佳)



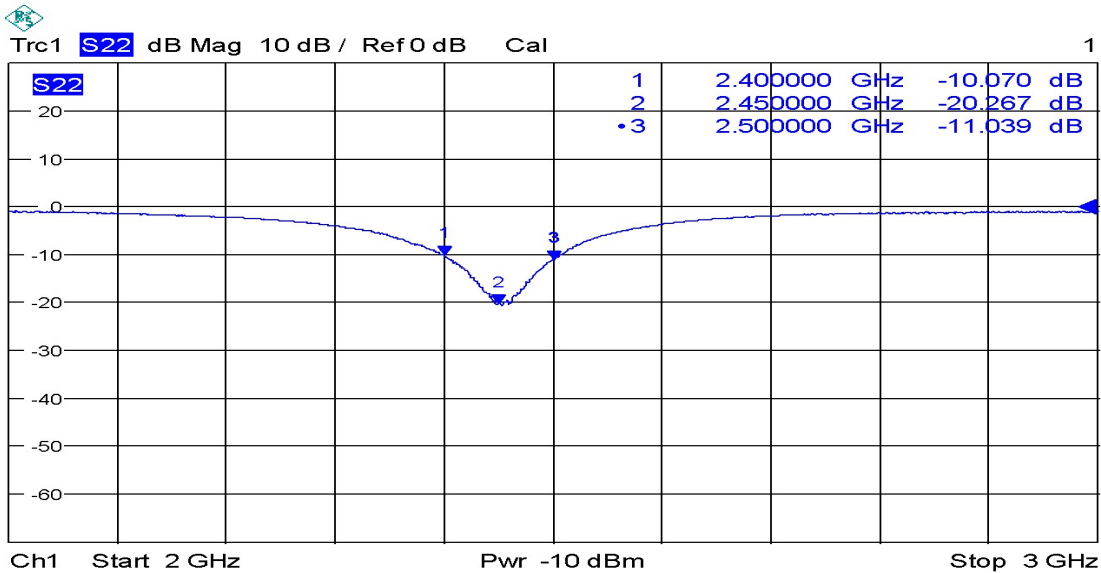
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FootPrint (Unit : mm)



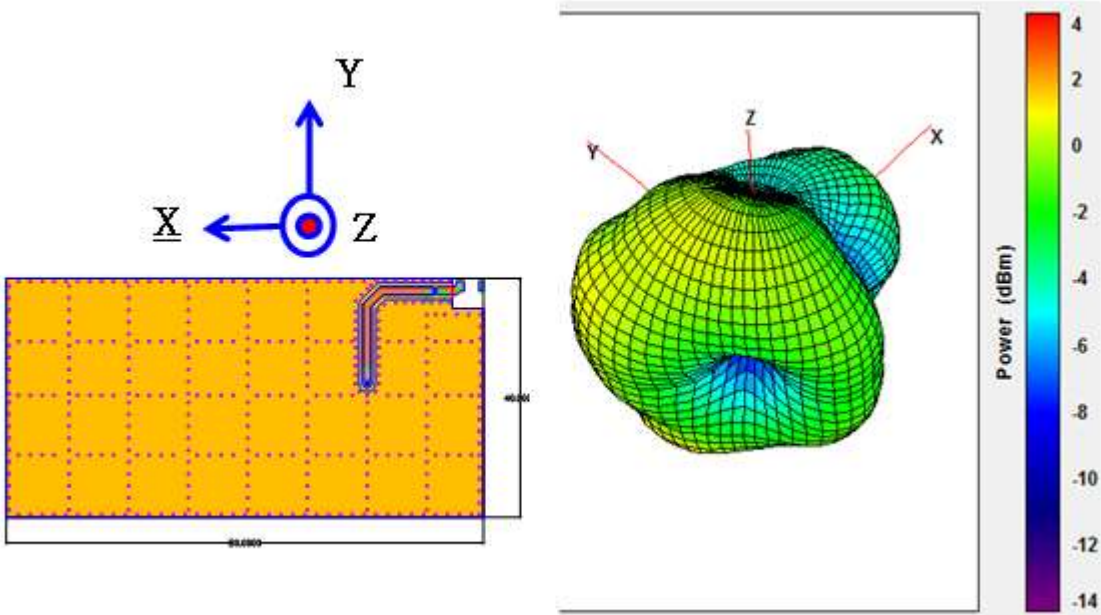
6.Measurement Results

Return Loss



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Radiation Pattern

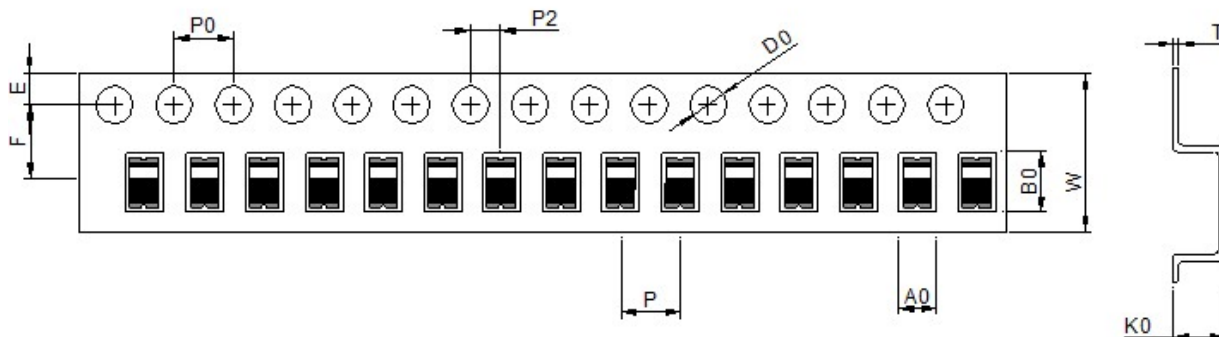


	Efficiency	Peak Gain
2400MHz	55.21 %	1.45 dBi
2450MHz	66.45 %	2.71 dBi
2500MHz	57.53 %	1.98 dBi

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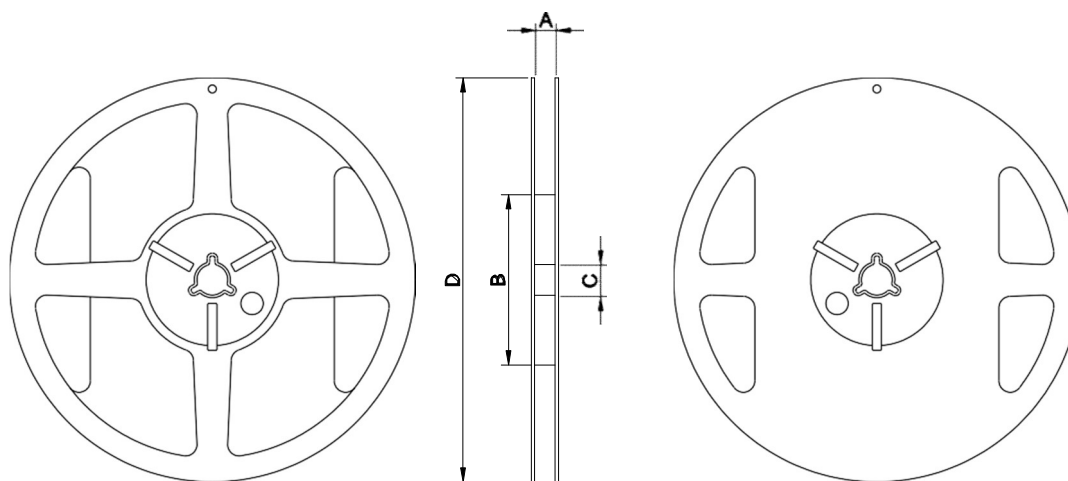
7. Packaging Information

Tape Specification:



W	Ao	Bo	Ko	P	F	E	D	D1	Po	P2	t
8.0 ±0.30	1.80 ±0.05	3.51 ±0.10	1.59 ±0.10	4.00 ±0.05	3.50 ±0.05	1.75 ±0.10	1.50 ±0.10	0.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.25 ±0.05

Reel Specification: (7", Φ180 mm)



7"x 8 mm

Tape Width(mm)	A(mm)	B(mm)	C(mm)	D(mm)	Chip/Reel(pcs)
8	9.0±0.5	60±2	13.5±0.5	178±2	3000

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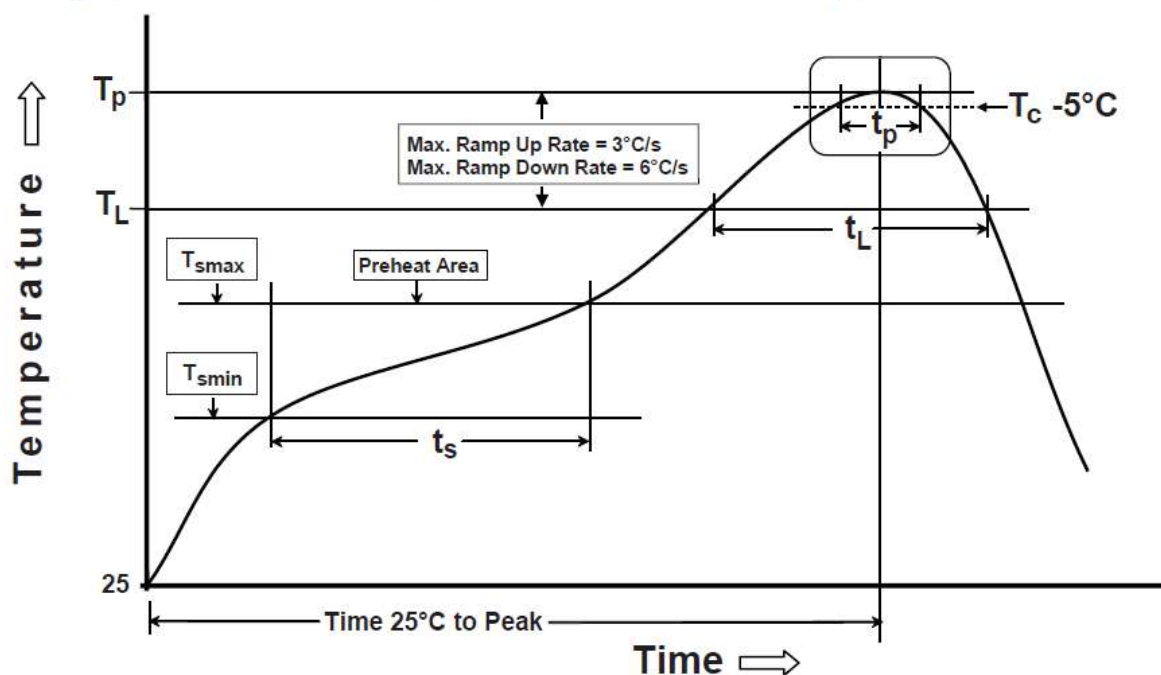
8. Recommended Reflow Temperature Profile

Cirocomm products can be assembled following Pb-free assembly. According to the Standard IPC/JEDEC J-STD-020C, the temperature profile suggested is as follow:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150°C 200°C 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217°C 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260°C 10 second
RAMP-DOWN	Rate	6°C / second max.
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

Note : All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

The graphic shows temperature profile for component assembly process in reflow ovens



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Soldering With Iron:

Soldering condition : Soldering iron temperature $270\pm 10^{\circ}\text{C}$.

Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature $270\pm 10^{\circ}\text{C}$ or 3 seconds, it will make component surface peeling or damage.
Soldering iron can not leakage of electricity.